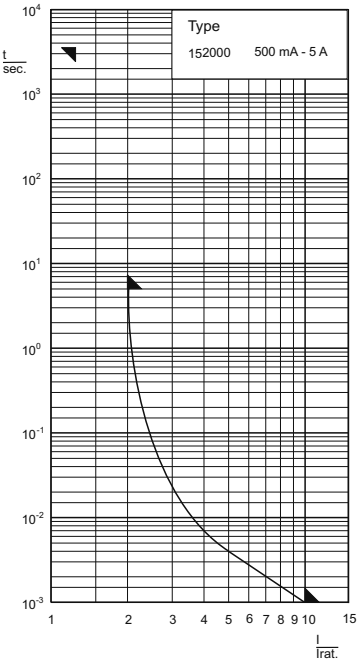
Type 152000

E167295



Zeit/Strom-Kennlinien
Time-Current Characteristics



Aufbau / Construction

Keramiksubstrat / ceramic substrate
Schmelzleiter gedruckt / printed fuse-element

Lötwärmebeständigkeit / resistance to soldering heat: (nach IEC 60068-2-58 / to IEC 60068-2-58)	260 °C, 10 s (Lötbad / solder bath) 260 °C, 10 s (reflow)
Vibration / vibration:	IEC 60068-2-6
Isolationswiderstand / insulation resistance	IEC 60127-4

Schmelzzeitgrenzwerte / Fusing time limits

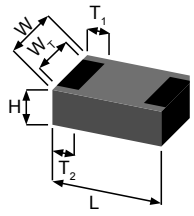
Bemessungsstrom Rated Current	1,25 I_n		2 I_n		2,75 I_n		4 I_n		10 I_n	
	min.		max.		min.		max.		min.	max.
500 mA - 5 A	1 h		5 s		-		-		-	1 ms

UL 248-14 IEC 60127-4	**0603** 1,55 x 0,85 mm	32 V	FF superflink very quick acting

Artikel-Nr. Article-no.	Bemessungs-strom Rated Current	Bemessungs-Ausschaltvermögen Rated Breaking Capacity	Spannungsfall Voltage Drop	Kalt-widerstand Cold Resistance	Schmelz-integral I^2t_s Value	Kenn-zeichnung Marking	Approbationen Approvals	
			mV	mΩ	A²s		UL rec.	VDE
152000.0,5	500 mA	50 A @ DC 32 V [1]	361	550	0,0009	F	✓	✓
152000.0,63	630 mA	50 A @ DC 32 V	331	400	0,0014	CT	✓	
152000.0,75	750 mA	50 A @ DC 32 V	258	262	0,002	G	✓	
152000.0,8	800 mA	50 A @ DC 32 V	249	237	0,0023	CV	✓	
152000.1	1 A	50 A @ DC 32 V [1]	223	170	0,0028	H	✓	✓
152000.1,25	1,25 A	50 A @ DC 32 V	180	110	0,0039	J	✓	
152000.1,5	1,5 A	50 A @ DC 32 V	155	79	0,0059	K	✓	
152000.1,6	1,6 A	50 A @ DC 32 V [1]	159	76	0,0065	EF	✓	✓
152000.1,75	1,75 A	50 A @ DC 32 V	138	60	0,0077	L	✓	
152000.2	2 A	50 A @ DC 32 V [1]	150	57	0,0101	N	✓	✓
152000.2,5	2,5 A	50 A @ DC 32 V	151	37	0,0157	O	✓	
152000.3	3 A	50 A @ DC 32 V	126	32	0,0227	P	✓	
152000.3,15	3,15 A	50 A @ DC 32 V [1]	120	29	0,025	EL	✓	✓
152000.3,5	3,5 A	50 A @ DC 32 V	106	23	0,0308	R	✓	
152000.4	4 A	50 A @ DC 32 V	100	19	0,0403	S	✓	
152000.5	5 A	50 A @ DC 32 V	85	13	0,2275	T		

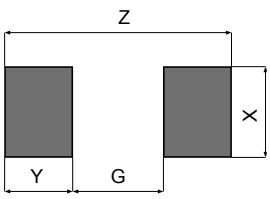
[1] 50 A @ DC 50 V mit/with VDE Approbation/approval

Abmessungen
Dimensions



H	0,45 +0,1 / -0,05 mm
L	1,55 ±0,05 mm
W	0,85 ±0,1 mm
W_T	> 75% von/of W
T_1	0,3 +0,15 / -0,2 mm
T_2	0,3 +0,15 / -0,2 mm

Empfohlene Anschlussflächen
Recommended pad layout



Lötung Soldering	Reflow Reflow	Welle Wave
G	0,5 mm	0,5 mm
X	0,95 mm	1,1 mm
Y	0,95 mm	1,2 mm
Z	2,4 mm	2,9 mm

Type	Abk. Abbr.	Beschreibung Description
152000	GT-1K	1.000 Stück gegurtet / 1.000 pieces on tape
	GT-5K	5.000 Stück gegurtet / 5.000 pieces on tape
	GT-20K	20.000 Stück gegurtet / 20.000 pieces on tape
z.B./ e.g.	152000.3,15GT-1K	

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